

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
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	§	Group Art Unit: 3742
Serial No.: 10/792,323	§	
	§	
Confirmation No.: 4370	§	
	§	Examiner: Sang Y. Paik
Filed: March 3, 2004	§	
	§	
For: Apparatus and Method for	§	
Vaporizing Solid Precursor	§	
for CVD or Atomic Layer	§	
Deposition	§	

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

RESPONSE TO OFFICE ACTION DATED MAY 3, 2006

In response to the Office Action dated May 3, 2006, having a shortened statutory period for response set to expire on August 3, 2006, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/005191.C1(Y1)/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 6 of this paper.